



PATENT ABSTRACTS OF JAPAN

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(54) MOVING BLADE THERMAL STRESS
REDUCING DEVICE

blade 1.

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(57) Abstract:

PROBLEM TO BE SOLVED: To reduce thermal stress generated on a moving blade so as to prevent generation of cracking on a thermal stress generating portion.

SOLUTION: For reducing thermal stress generated on a moving blade 1 by an uneven temperature difference generated on the moving blade 1 by a high temperature operating fluid 03 which flows an outer periphery and a cooling medium so as to prevent generation of a high temperature by the operating fluid 03, a plurality of slits 5 are arranged in the direction perpendicular to a direction of a generating thermal stress 4 on a thermal stress generation part 2 of the moving blade 1 where thermal stress is generated so as to reduce the magnitude of thermal stress acted on the moving blade 1 by absorbing thermal deformation of the moving blade 1 generated by the heat stress 4. Accordingly, thermal stress is released and reduced by deformation of a gap between the slits 5, and it is also possible to prevent generation of cracking generated on the moving

